



Revision: 1.0
Date: 5-Mar-05

Statement of Materials, Construction

LEAD-FREE -- 8L-DFN -- TABLE OF MATERIAL DECLARATION

No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Cu Alloy	0.00461	Cu	7440-50-8	0.004429	19.7871	95.994
				Fe	7439-89-6	0.000107	0.4769	2.314
				Zn	7440-66-6	0.000005	0.0244	0.118
				P	7723-14-0	0.000001	0.0061	0.030
				Spot Plating (Ag)	7440-22-4	0.000072	0.3185	1.569
2	Die	Silicon Chip	0.00230	Si	7440-21-3	0.002285	10.0507	99.5
3	Die Attach Material	Conductive Epoxy	0.00033	Silver	7440-22-4	0.000246	1.0816	75
				Epoxy Resin	Proprietary	0.000049	0.2163	15
				Amine	Proprietary	0.000011	0.0476	3.3
				Gamma Butyrolactone	96480	0.000011	0.0476	3.3
				Metal Oxide	Proprietary	0.000011	0.0476	3.3
4	Gold Wire	Gold	0.00008	Au	7440-57-5	0.000084	0.3684	99.99
5	Lead Finish	Tin	0.00039	Sn	7440-31-5	0.000388	1.7078	100
6	Encapsulation	Epoxy Resin	0.01502	Silica Fused	60676-86-0	0.013521	59.4774	90
				Epoxy Resin	Proprietary	0.000751	3.3043	5
				Phenol Resin	Proprietary	0.000526	2.3130	3.5
				Carbon Black	1333-86-4	0.000075	0.3304	0.5
				Brominated Epoxy Resin	40039-93-8	0.000075	0.3304	0.5
				Antimony trioxide	1309-64-4	0.000075	0.3304	0.5
Total Package weight			0.02273					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys